

650V N-Channel Power MOSFET

DESCRIPTION :

- Fast Switching Capability
- Extremely Low Gate Charge
- 100% UIS Tested, 100% Rg Tested
- Excellent Output Capacitance (Coss) Profile
- RoHS compliant
- Pb-Free Lead Plating

V_{DS}	650V
$I_D @ V_{GS}=10V$	20A
$R_{DS(ON_Typ. @ V_{GS}=10V}$	168m Ω

TYPICAL APPLICATIONS :

- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter
- UPS / Solar



TO-247-3L

MAXIMUM RATINGS (at $T_A = 25^\circ\text{C}$, unless otherwise specified)

Characteristic	Condition	Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	650	V
Gate-Source Voltage		V_{GS}	± 30	V
Continuous Drain Current	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	I_D	20 12.1	A
Pulsed Drain Current ⁽¹⁾		I_{DM}	75	A
Avalanche Current ⁽²⁾		I_{AS}	9	A
Avalanche Energy ⁽²⁾		E_{AS}	405	mJ
Power dissipation	$T_c=25^\circ\text{C}$ $T_c=100^\circ\text{C}$	P_D	189 76	W
Junction & Storage temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

Notes : 1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. The single-pulse measurement was taken under the following condition [$V_{DS}=50V, V_{GS}=10V, L=10\text{mh}$] while its value is limited by $T_{JMAX} = 150^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Condition	Symbol	Value	Unit
Thermal resistance,	Junction to Ambient Junction to Case	$R_{\theta JA}$ $R_{\theta JC}$	60 0.8	$^\circ\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS (at $T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage VGS = 0V, ID = 250uA	$V_{(BR)DSS}$	650			V
Zero Gate Voltage Drain Current VDS = 650 V, VGS = 0 V	I_{DSS}			10	uA
Gate-Source Leakage Current VGS = ± 30 V, VDS = 0V	I_{GSS}			± 100	nA
Gate-Source threshold voltage VDS = VGS, ID = 250uA	$V_{GS(th)}$	2.5	3.5	4.5	V
Drain-Source On-State Resistance VGS = 10V, ID = 10A	$R_{DS(on)}$		168	190	m Ω
Input capacitance f=1MHz, VDS=100 V, VGS=0 V	C_{iss}		1560		pF
Output capacitance f=1MHz, VDS=100 V, VGS=0 V	C_{oss}		61		pF
Reverse transfer capacitance f=1MHz, VDS=100 V, VGS=0 V	C_{rss}		11.7		pF
Gate Resistance VDS=0 V, VGS= 0V, f=1MHz	R_g		8.9		Ω
Total Gate Charge VDS= 325V, ID= 10A, VGS=0 to 10V	Q_G		38		nC
Gate to Source Charge VDS= 325V, ID= 10A, VGS=0 to 10V	Q_{GS}		10.1		nC
Gate to Drain Charge VDS= 325V, ID= 10A, VGS=0 to 10V	Q_{GD}		14.8		nC
Turn-on delay time VDS=325 V, VGS= 10V, $R_L=32.5\Omega$, $R_{GEN}=6\Omega$	$t_{d(ON)}$		17.8		ns
Rise time VDS=325 V, VGS= 10V, $R_L=32.5\Omega$, $R_{GEN}=6\Omega$	t_r		22		ns
Turn-off delay time VDS=325 V, VGS= 10V, $R_L=32.5\Omega$, $R_{GEN}=6\Omega$	$t_{d(OFF)}$		257		ns
Fall time VDS=325 V, VGS= 10V, $R_L=32.5\Omega$, $R_{GEN}=6\Omega$	t_f		20		ns

Body Diode

ELECTRICAL CHARACTERISTICS (at $T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Diode Forward Voltage $V_{GS} = 0V, I_S = 1A$	V_{SD}		0.75	1.0	V
Diode Continuous Current, $T_c=25^\circ\text{C}$	I_S			189	A
Revers Recovery Time $I_F=10A, dI_F/dt = 100A/us$	T_{rr}		340		ns
Revers Recovery Charge $I_F=10A, dI_F/dt = 100A/us$	Q_{rr}		4.4		nC

Typical Performance Characteristics

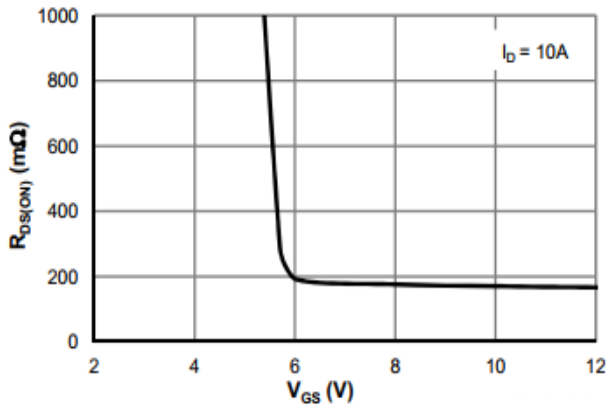


Figure 1. $R_{DS(ON)}$ vs. V_{GS}

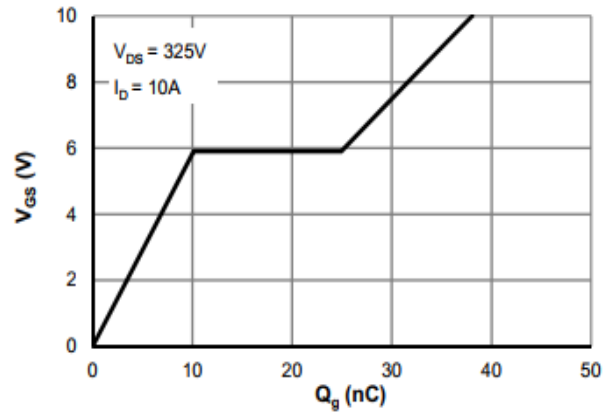


Figure 2. Gate Charge Characteristics

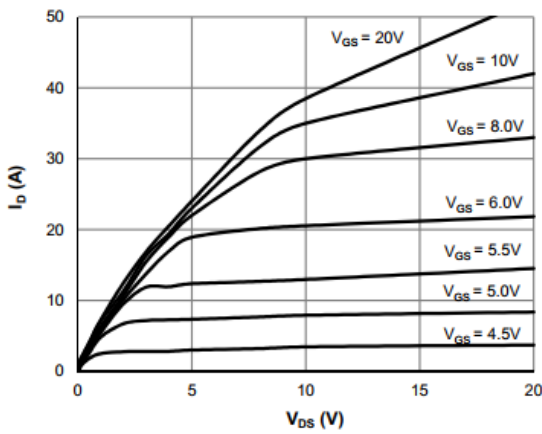


Figure 3. Saturation Characteristics

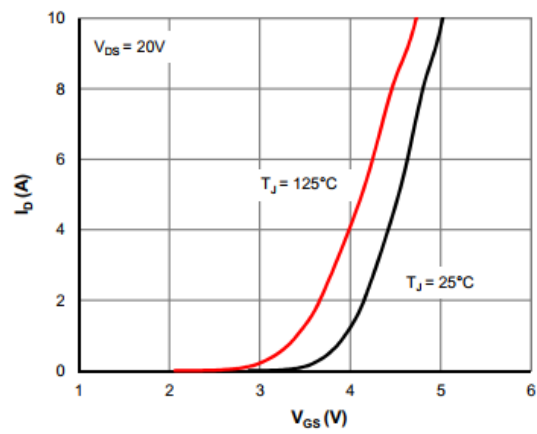


Figure 4. Transfer Characteristics

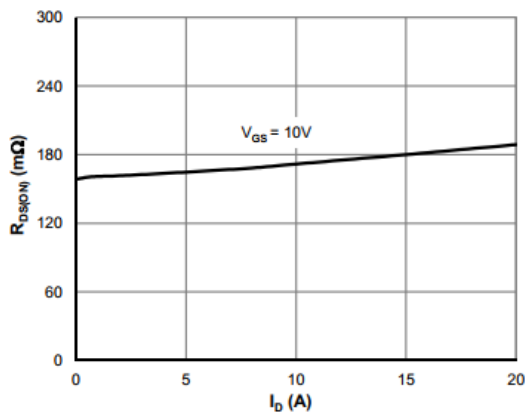


Figure 5. On-resistance vs. Drain Current

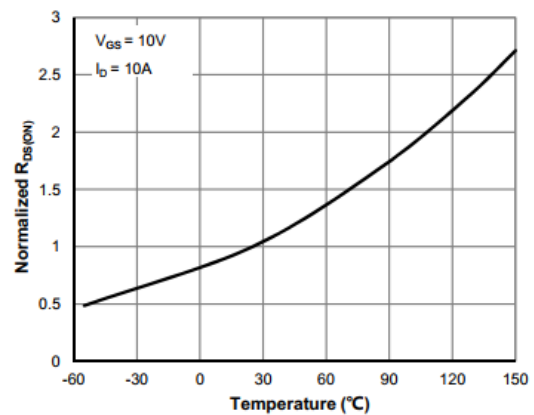


Figure 6. $R_{DS(ON)}$ vs. Junction Temperature

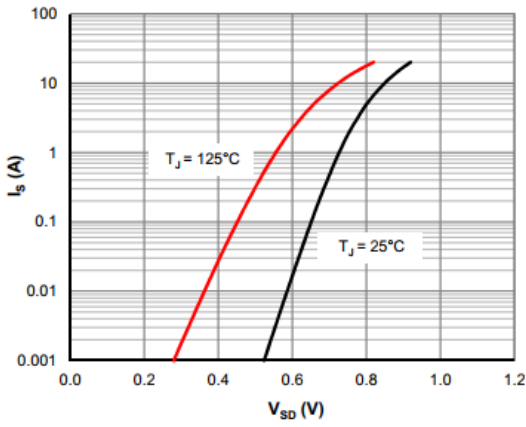


Figure 7. Body-Diode Characteristics

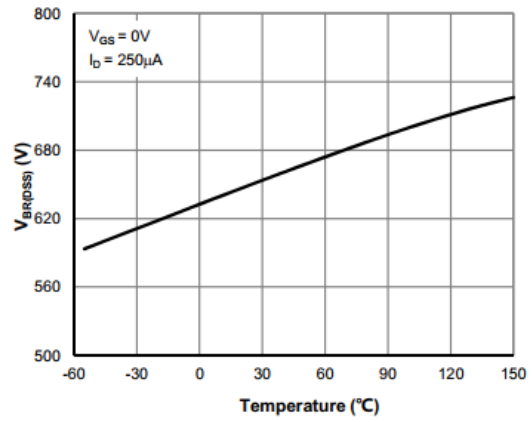


Figure 8. $V_{BR(DSS)}$ vs. Junction Temperature

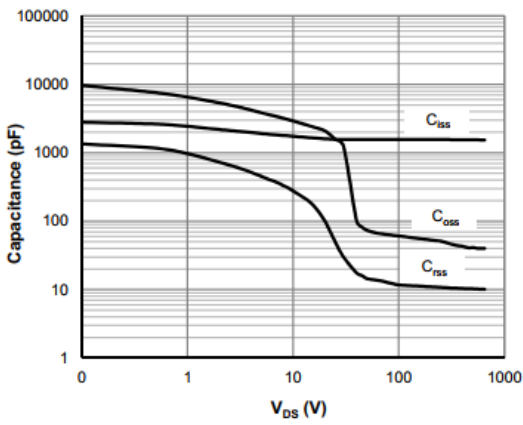


Figure 9. Capacitance Characteristics

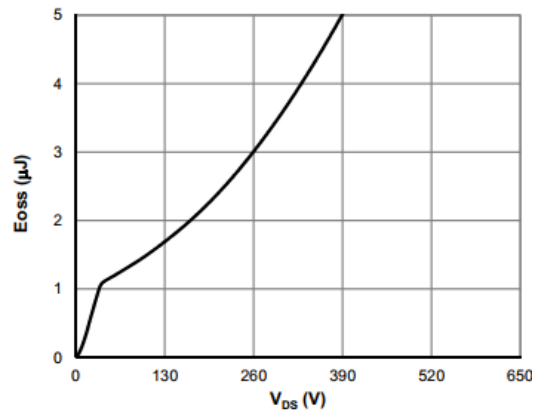


Figure 10. C_{oss} Stored Energy

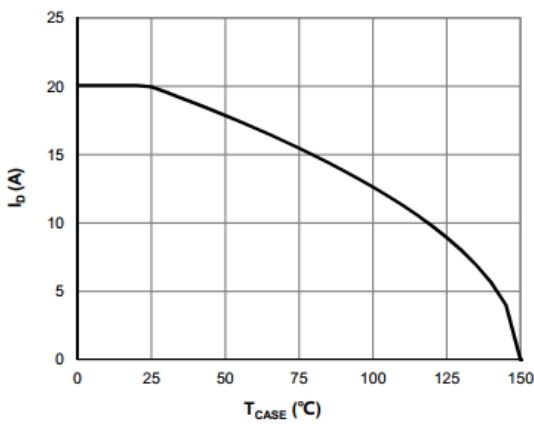


Figure 11. Current De-rating

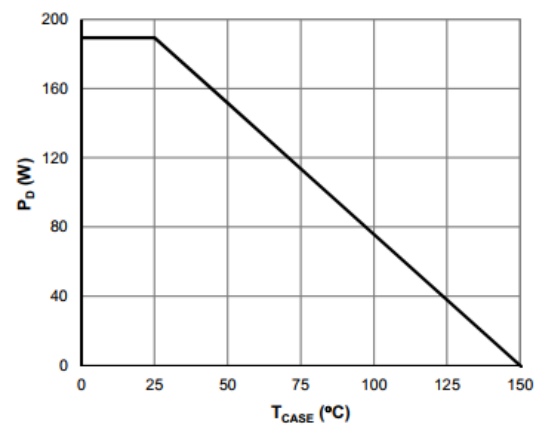


Figure 12. Power De-rating

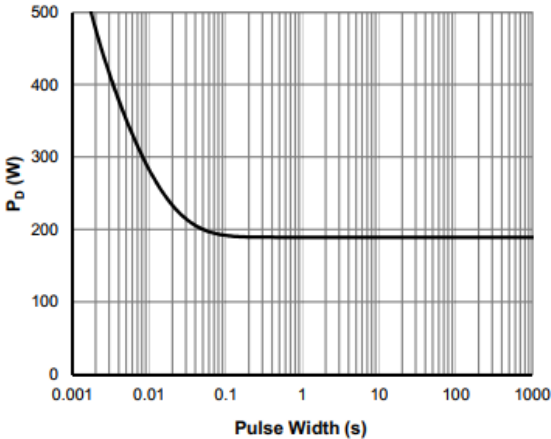


Figure 13. Single Pulse Power Rating, Junction-to-Case

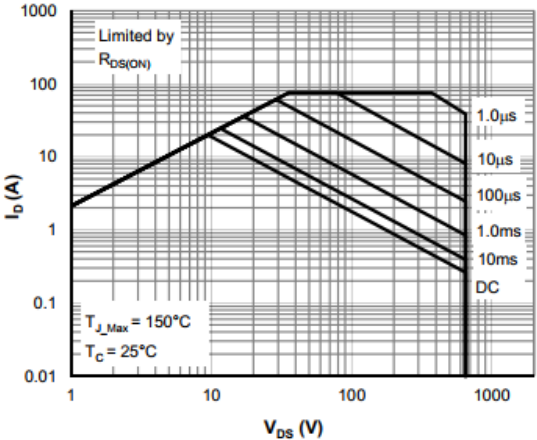


Figure 14. Maximum Safe Operating Area

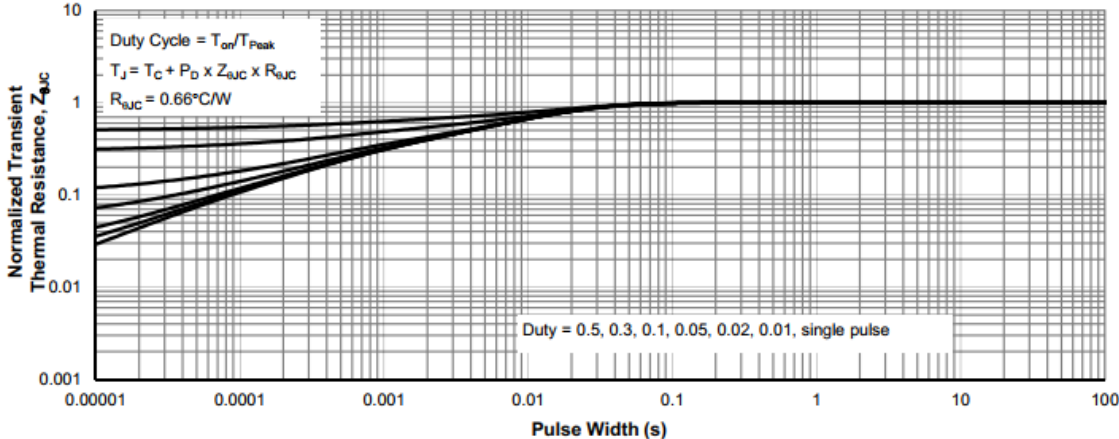
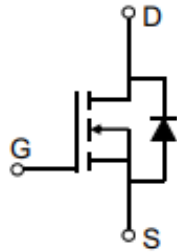
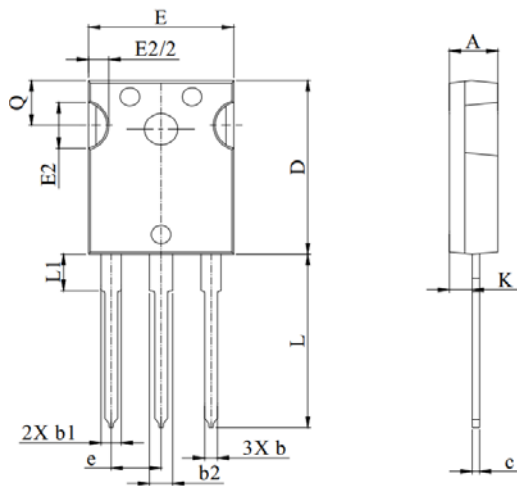


Figure 15. Normalized Maximum Transient Thermal Impedance

- Circuit diagram



- Package outlines :



Dimensions	Millimeters	
	Min	Max
A	4.80	5.21
b	1.00	1.40
b1	1.90	2.39
B2	2.87	3.22
c	0.41	0.79
D	20.80	21.20
E	15.50	16.13
E2	4.32	5.49
L	19.70	20.32
L1	4.00	4.40
K	2.20	2.50
e	5.44 BSC	

Notice

MOSPEC reserves the rights to make changes of the content herein the document anytime without notification. MOSPEC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies. Please refer to MOSPEC website for the last document.

MOSPEC disclaims any and all liability arising out of the application or use of any product including damages incidentally and consequentially incurred.

Application shown on the herein document are examples of standard use and operation. Customers are responsible for comprehending suitable use in particular applications. MOSPEC makes no representation or warranty that such application will be suitable for the specified use without further testing or modification.

The information contained herein is presented only as a guide for the applications of our products. No responsibility is assumed by MOSPEC for any infringements of patents or other rights of the third parties which may result from its use. No license is granted by implication or otherwise under any patent or patent rights of MOSPEC or others.

These MOSPEC products are intended for usage in general electronic equipment. Please make sure to consult with MOSPEC before you use these MOSPEC products in equipment which require specialized quality and/or reliability, and in equipment which could have major impact to the welfare of human life (atomic energy control, aeronautics , traffic control, combustion control, safety devices etc.)